

## CPMT Officers

<b>President:</b>	William T. Chen	+1-408-986-6505
<b>VP (Technical):</b>	N.Rao Bonda	+1-480-413-6121
<b>VP (Conferences):</b>	Rolf Aschenbrenner	+49-30-46403-164
<b>VP (Publications):</b>	R. Wayne Johnson	+1-334-844-1880
<b>VP (Education):</b>	Albert F. Puttlitz	+1-802-899-4692
<b>VP (Finance):</b>	Thomas G. Reynolds III	+1-850-897-7323
<b>Sr. Past Pres.:</b>	Rao Tummala	+1-404-894-9097
<b>Jr. Past Pres.:</b>	Phil Garrou	+1-919-248-9261
<b>Executive Director:</b>	Marsha Tickman	+1-732-562-5529

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- 2010:** Eric O. Beyne, Steve J. Bezuk, Kitty Pearsall, Eric Perfecto, Ephraim Suhir and C.P. Wong
- 2011:** Vasudeva Atluri, Patrick Thompson, Paul Wesling, Klaus-Jurgen Wolter, Jie Xue, and Kishio Yokouchi

## CPMT Society Newsletter

<b>Editor-in-Chief:</b>	Vasudeva P. Atluri, email: <a href="mailto:vpatluri@ieee.org">vpatluri@ieee.org</a> Tel: +1-480-227-8411, FAX: +1-480-563-0049
<b>Associate Editor:</b>	Li Li, <a href="mailto:li.li@ieee.org">li.li@ieee.org</a> , +1-480-413-6653
<b>Associate Editor:</b>	Debendra Mallik, <a href="mailto:dmallik@ieee.org">dmallik@ieee.org</a> , +1-480-554-5328

## CPMT Archival Publications

### Publications VP:

R. Wayne Johnson, +1-334-844-1880; [johnsr7@auburn.edu](mailto:johnsr7@auburn.edu)

### Editor-in-Chief, CPMT Transactions:

Avram Bar-Cohen, Univ. of Maryland, +1-301-405-3173, [abc@eng.umd.edu](mailto:abc@eng.umd.edu)

### Transactions on Components & Pkg. Technologies, Editors in Chief:

Ricky S.W. Lee, Hong Kong Univ of Science & Technology, +852-2358-7203; [rickleey@ust.hk](mailto:rickleey@ust.hk)

Koneru Ramakrishna, Freescale, Inc., +1-512-933-2555; [rama@ieee.org](mailto:rama@ieee.org)

### Transactions on Advanced Packaging, Editor in Chief:

G. Subbarayan, Purdue University, Mechanical Engineering Dept., +1-765-494-9770; [ganeshs@purdue.edu](mailto:ganeshs@purdue.edu)

José E. Schutt-Ainé, University of Illinois at Urbana-Champaign, +1-217-244-7279, [jose@emlab.uiuc.edu](mailto:jose@emlab.uiuc.edu)

### Transactions on Electronics Pkg. Manufacturing, Editor in Chief:

R. Wayne Johnson, +1-334-844-1880, [johnsr7@auburn.edu](mailto:johnsr7@auburn.edu)

## Technical Committee Chairs

### TC-Assy - IC and Package Assembly:

Martin Goetz, IBM, +1-919-486-2409, [mgoetz@us.ibm.com](mailto:mgoetz@us.ibm.com)

### TC-ASTR - Environmental Stress & Reliability Test:

John E. Proulx, GM ATC, +1-310-257-3714, [john.proulx@gm.com](mailto:john.proulx@gm.com)

### TC-ECCC - Electrical Contacts, Connectors and Cables:

Jerry Witter, Chugai USA Inc., +1-847-244-6025, [g.witter@ieee.org](mailto:g.witter@ieee.org)

### TC-Ed - Education:

Rao R. Tummala, Georgia Tech., +1-404-894-9097, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

### TC-EDMS - Electrical Design, Modeling and Simulation:

Madhavan Swaminathan, Georgia Tech, +1-404-894-3340, [madhavan.swaminathan@ee.gatech.edu](mailto:madhavan.swaminathan@ee.gatech.edu)

### TC-EM - Manufacturing - Design & Process:

Walter J. Trybula, SEMATECH, +1-512-356-3306, [w.trybula@ieee.org](mailto:w.trybula@ieee.org)

### TC-GEMP - Green Electronics Manufacturing and Packaging:

Nils F. Nissen, IZM, Berlin, +49-30-46403-139, [nils.nissen@izm.fraunhofer.de](mailto:nils.nissen@izm.fraunhofer.de)

### TC-HDSB - High Density PWB Packaging:

Yoshitaka Fukuoka, Weisti, +81-3-3475-0755, [weisti.fukuoka@rose.zero.ad.jp](mailto:weisti.fukuoka@rose.zero.ad.jp)

### TC-M - Materials:

Rajen Chanchani, Sandia Labs, +1-505-844-3482, [r.chanchani@ieee.org](mailto:r.chanchani@ieee.org)

### TC-MEMS - MEMS and Sensor Packaging:

Eric Jung, IZM, Berlin, +49-30-46403-161, [erju@izm.fhg.de](mailto:erju@izm.fhg.de)

### TC-NANO - Nano Packaging:

Rao Tummala, Georgia Tech., +1-404-894-9097, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

### TC-OPTO - Fiber Optics & Photonics:

Susan Law, Australian Photonics/OFTC, +612-9351-1960, [s.law@ofc.usyd.edu.au](mailto:s.law@ofc.usyd.edu.au)

### TC-PEP - Power Electronics Packaging:

Douglas Hopkins, SUNY Buffalo, +1-607-729-9949, [d.hopkins@ieee.org](mailto:d.hopkins@ieee.org)

### TC-RF+W - RF and Wireless:

Craig A. Gaw, Freescale, +1-480-413-5920, [c.a.gaw@ieee.org](mailto:c.a.gaw@ieee.org)

### TC-SP - Systems Packaging:

Cian O Mathuna, +353-21-4904350, [cian.omathuna@tyndall.ie](mailto:cian.omathuna@tyndall.ie)

### TC-Test - Electrical Test:

Bruce Kim, Univ of Alabama, +1-205-348-4972, [bruce.kim@ieee.org](mailto:bruce.kim@ieee.org)

### TC-Therm - Thermal Management & Thermomech. Design:

Tony Mak, Dallas Semiconductor, +1-972-371-4364, [t.mak@ieee.org](mailto:t.mak@ieee.org)

### TC-WLP - Wafer Level Packaging:

Michael Toepper, IZM, Berlin, +49-30-46403-603, [toepper@izm.fhg.de](mailto:toepper@izm.fhg.de)

## Strategic Program Directors

**Awards and Recognition:** Kitty Pearsall, [kittyp@us.ibm.com](mailto:kittyp@us.ibm.com)

**Conferences:** Rolf Aschenbrenner, [wdb@engr.uark.edu](mailto:wdb@engr.uark.edu)

**ECTC Integration:** C.P. Wong, [cp.wong@ieee.org](mailto:cp.wong@ieee.org)

**Educational Programs:** Albert F. Puttlitz, [a.f.puttlitz@ieee.org](mailto:a.f.puttlitz@ieee.org)

**Global Chapters and Membership:** Steve Bezuk, [sbezuk@qualcomm.com](mailto:sbezuk@qualcomm.com)

**Publications:** R. Wayne Johnson, [johnsr7@auburn.edu](mailto:johnsr7@auburn.edu)

**Student Programs:** Vacant

**Technical Programs:** N.Rao Bonda, [r.bonda@ieee.org](mailto:r.bonda@ieee.org)

**Region 8 Programs:** Eric Beyne Beyne@imec.be

**Region 10 Programs:** Charles Lee, [charles.lee@ieee.org](mailto:charles.lee@ieee.org)

## Standing Committee Chairs

**Awards:** Kitty Pearsall, [kittyp@us.ibm.com](mailto:kittyp@us.ibm.com)

**Chapter Development:** Steve Bezuk, [sbezuk@qualcomm.com](mailto:sbezuk@qualcomm.com)

**Constitution and Bylaws:** Tony Mak, [t.mak@ieee.org](mailto:t.mak@ieee.org)

**Distinguished Lecturers:** Albert F. Puttlitz, [a.f.puttlitz@ieee.org](mailto:a.f.puttlitz@ieee.org)

**Educational Activities:** Vacant

**Fellows Evaluation:** Ching-Ping (C.P.) Wong, [cp.wong@ieee.org](mailto:cp.wong@ieee.org)

**Fellows Search:** David W. Palmer, [d.palmer@ieee.org](mailto:d.palmer@ieee.org)

Rao Tummala, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

**Finance:** Philip E. Garrou, [pgarrou@rti.com](mailto:pgarrou@rti.com)

**Long Range / Strategic Planning:** Rao Tummala, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

**Membership:** Steve Bezuk, [sbezuk@qualcomm.com](mailto:sbezuk@qualcomm.com)

**Nominations:** Philip E. Garrou, [pgarrou@rti.com](mailto:pgarrou@rti.com)

## Distinguished Lecturers

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Refer to [www.cpmpt.org](http://www.cpmpt.org) for CPMT Society Chapters and Student Branches list

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